

MAINTENANCE MANUAL

800 MHz, 15 WATT TRANSMITTER/RECEIVER BOARD (SIMPLEX) 19D900742G10

GE MARC VOE CLASSIC II

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DESCRIPTION

The transmitter/receiver board contains the fixed tuned power amplifier module, power control circuit and the 800 MHz receiver. Component parts for the exciter are located on the synthesizer/interconnect board and the transmitter/receiver board. The frequency synthesizer and frequency injection chain including a frequency tripler are located on the synthesizer/interconnect board. The transmitter/receiver board is mounted on the bottom side of the "H" frame chassis.

The exciter provides approximately 250 milliwatts of modulated RF power to the PA module which provides 15 watts power output. Figure 1 is a block diagram of the GE-MARC V \bullet E radio showing both the transmitter and receiver.

TRANSMITTER

EXCITER

The synthesized frequency output and the injection output from the interconnect/frequency synthesizer board are applied to the balanced mixer through J101 and J102. The mixer output signal is the sum of these two input signals and will fall within the range of 408-410.5 MHz. The output of the balanced mixer is coupled through three tuned circuits (L101, L102, L103) to the base of amplifier Q101. Metering test point TP101 is used in tuning L101, L102 and L103. The typical DC reading is 5.6 volts.

CIRCUIT ANALYSIS

Following amplifier Q101 is frequency doubler Q102. The output of 102 (816-821 MHz) is filtered by L107,

L108, and L109, and are tuned to the operating frequency. The filter output is applied to the base of amplifier Q103.

The collector output of Q103 is applied to a power splitter consisting of L111 and C116, and L112 and C121. The portion of the RF signal Vcoupled through L111 and C116 is applied to the base of amplifier Q104. The output of Q104 is coupled to the receiver and used as the 1st oscillator injection frequency. The signal coupled through L112 and C121 is applied to the base of exciter amplifier Q105. The collector tank of Q105 is tuned by C125 and C127.

Following Q105 is amplifier Q106. The output of Q106 is tuned by C133 and C134.

Variable capacitors C125, C127, C133 and C134 are tuned for a maximum DC voltage reading at TP103. The typical DC reading at TP103 is 1.6 volts. Part of the RF signal at W102 is rectified by "sniffer" diode D101 to provide the voltage reading at TP103.

W102 is a 50 ohm stripline on the printed circuit board that matches the exciter output to the PA input impedance.

POWER AMPLIFIER

Power amplifier U102 is a three stage amplifier that amplifies the 250 milliwatt exciter output to provide a 15 watt output. The output of U102 is coupled through 50 ohm stripline W104 to low pass filter A102. The filter output is applied to antenna relay K601.

RF POWER CONTROL CIRCUIT

The output power adjust circuit allows the RF output power to be set to rated output power. The power adjustment



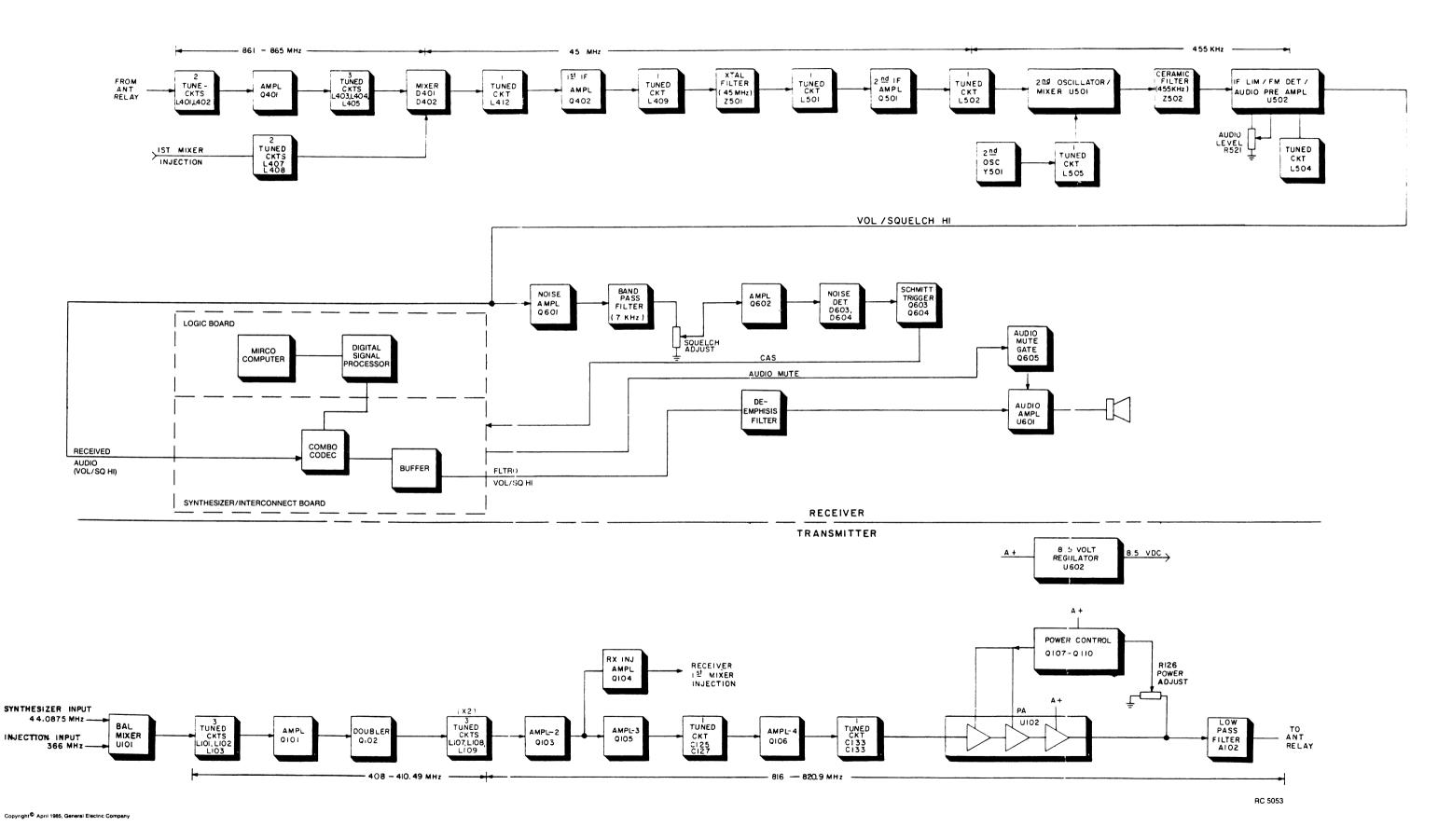


Figure 1 - Transmitter/Receiver Block Diagram

is attained by controlling the DC collector voltage to the pre-driver and driver stages in U102 through pass transistor Q110. The pass transistor is controlled by a feedback loop consisting of Q107 through Q109. The power is set by potentiometer R126.

Any change in output power is sensed by the power control circuit. For example: if the output power increases, more RF is rectified by D102, increasing the base voltage of Q107. This causes Q107 to conduct more, reducing its collector voltage (and base voltage to Q108).

Reducing the base voltage applied to Q107 causes it to conduct less, raising the base voltage of PNP transistor Q109. With Q109 conducting less, there is less base voltage applied to pass transistor Q110 resulting in less collector voltage being applied to the pre-driver and driver stages in U102. This reduces the output power of the PA module in proportion to the increase in output power detected at the base of Q107. TP104 is used to check the DC control voltage being applied to the power amplifier; typically this voltage is 9.0 VDC.

RECEIVER

GE MARC V•F 800 MHz receivers are dual conversion, superheterodyne FM receivers designed for operation in the 861-865 MHz frequency range. A regulated 8.5 volts is used for all receiver stages except for the audio PA IC, which operates from the A+ supply.

The receiver uses intermediate frequencies of 45.0125 MHz and 455 kHz. Adjacent channel selectivity is obtained by using two bandpass filters: a 45 MHz crystal filter and a 455 kHz ceramic filter.

All receiver circuitry is mounted on the transmitter/receiver Tx/Rx) board. The receiver consists of:

- Receiver Front End and 1st Mixer
- 45.0125 MHz 1st IF circuitry
- 2nd Oscillator
- 455 kHz 2nd IF circuitry with FM Detector
- Audio PA Circuit
- Squelch Circuit

RECEIVER FRONT END

RF from the antenna is coupled through two helical resonators (L401 and

L402) to the base of RF amplifier Q401. Q401 is a class A, common emitter amplifier that provides a gain of approximately 8 to 10 dB. The amplified output is coupled through three additional helicals to the 1st mixer. The five helicals provide the front end selectivity.

1ST MIXER

The 1st mixer is a dual balanced diode mixer that converts a signal in the 861-865 MHz range to the 45 MHz 1st IF frequency.

RF from the front end helicals is coupled through C404 to mixer diodes D401 and D402. The low side injection input from the exciter is coupled through two helicals (L407 and L408) to the mixer diodes. The injection input port is isolated from the RF input and IF output by a balancing transformer consisting of L413 tapped to ground.

The 1st mixer output is coupled through a tuned circuit (L412 and C405) that matches the mixer output to gate 1 of 1st IF amplifier Q402.

TP401 is used in tuning the discrete IF stages and the injection filter, L408 and L409.

1ST IF AMPLIFIER AND FILTER

IF Amplifier Q402 is a dual gate FET that provides good intermodulation and desensitization characteristics. The amplifier also acts as a buffer between the variable balanced mixer output impedance and the crystal filter.

The 45.0125 MHz output signal at the drain of Q402 is coupled through a tuned circuit (L409 and C408) that sets the impedance to crystal filter Z501.

Z501 is a 45.0125 MHz, four-pole crystal filter that provides a minimum of 30 dB adjacent channel rejection. The filter output is applied through a tuned circuit (L501, C501 and C526) that matches the output impedance of Z501 to the second IF amplifier.

2ND IF AMPL

2nd IF Amplifier Q501 is a dual-gate FET. The filter output is applied to Gate 1 of the amplifier, and the output is taken from the drain. The biasing on Gate 2 and the drain load determines the gain of the stage. The amplifier provides approximately 20 dB of IF gain. The output of Q501 is coupled through L502 which matches the amplifier output to the input of IC U501.

2ND OSC/MIXER AND IF AMPL

The 2nd oscillator, mixer and 3rd IF amplifier consists of U501 and associated circuitry. The oscillator operates at 45.455 MHz for high side injection (45.4675 MHz-offset IF). The oscillator crystal is Y501. The 45 MHz input frequency is mixed with the oscillator frequency to provide the 2nd IF frequency of 455 kHz. Diodes D501 and D502 limit the mixer output. L503 is tuned for the 2nd IF output of 455 kHz.

FILTER, LIMITER AND DETECTOR

The output of U501 is coupled through ceramic filter Z502 which provides the 455 kHz selectivity, and applied to U502. Test Point TP501 is used in aligning the receiver, and can be used to check the output of U501. The typical DC reading at TP501 is 2.7 volts.

U502 and associated circuitry consists of a 455 kHz limiter, a quadrature-type FM detector and an audio pre-amplifier. L504 is the quadrature detector coil. Audio Level Potentiometer R521 is used to set the audio output level to the audio amplifier.

AUDIO AND SQUELCH CIRCUITS

<u>Audio</u>

Audio from the audio pre-amplifier U502 is applied to the combo codec (U2514 on the Synthesizer/Interconnect board). The analog audio is converted to a serial format whereby a digital signal processor fiters the audio. The signal processor performs the busy tone notching, tone detection, alert tone generation and volume control.

After processing, the FLTRD VOL/SQ HI signal is derived from the combo codec and is buffered over to the T/R board. This same buffered signal is deemphasized, amplified and sent over to the handset.

On the T/R board, the FLTRD VOL/SQ HI (buffered signal) is de-emphasized by R629 and C608 and amplified by U601. The audio amplifier IC (U601) drives the speaker at the desired audio level. The feedback loop containing R633, R634 and C610 determines the amplifier closed loop gain. R631 and C612 provide the high audio frequency roll-off above 6 kHz.

Squelch

The squelch circuit operates on the noise components contained in the FM detector output. The output of U502 is applied to frequency selective noise amplifier Q601 that has a resonant circuit (L601, R604 and C602) as the collector load. The output is noise in a band around 7 kHz.

This noise output is coupled through Squelch control R607 to expander amplifier Q602 which improves the level discrimination characteristics of the circuit. The output of Q602 is applied to a passive voltage doubler circuit (D603 and D604). This circuit has a high source impedance an operates as an average value rectifier.

Following the voltage doubler is a Schmidt Trigger (Q603 and Q604). The Schmidt Trigger provides the necessary hysteresis and a well-defined output signal for Rx mute gate Q605.

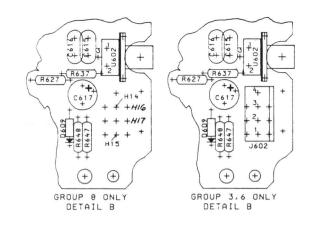
With no RF signal present, the detected noise at the voltage doubler output turns on Q603, turning off Q604. This causes Q605 to turn on, applying +1.7 volts to pin 2 of audio amplifier U601. This voltage turns off U601 and mutes the receiver.

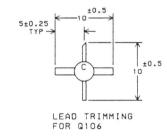
When an RF signal is received, the noise at the output of Q601 decreases and drive to Q603 is removed. This turns off Q603 and allows Q604 to turn on. With Q604 turned on, Rx mute gate Q605 turns off. This turns on U601 so that audio is heard at the speaker.

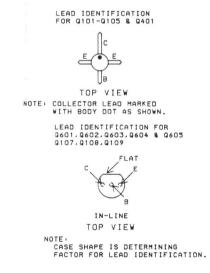
The squelch sensitivity is adjusted by R607 in the base circuit of expander amplifier Q602.

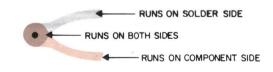
GENERAL ELECTRIC COMPANY • MOBILE COMMUNICATIONS DIVISION WORLD HEADQUARTERS • LYNCHBURG, VIRGINIA 24502 U.S.A.







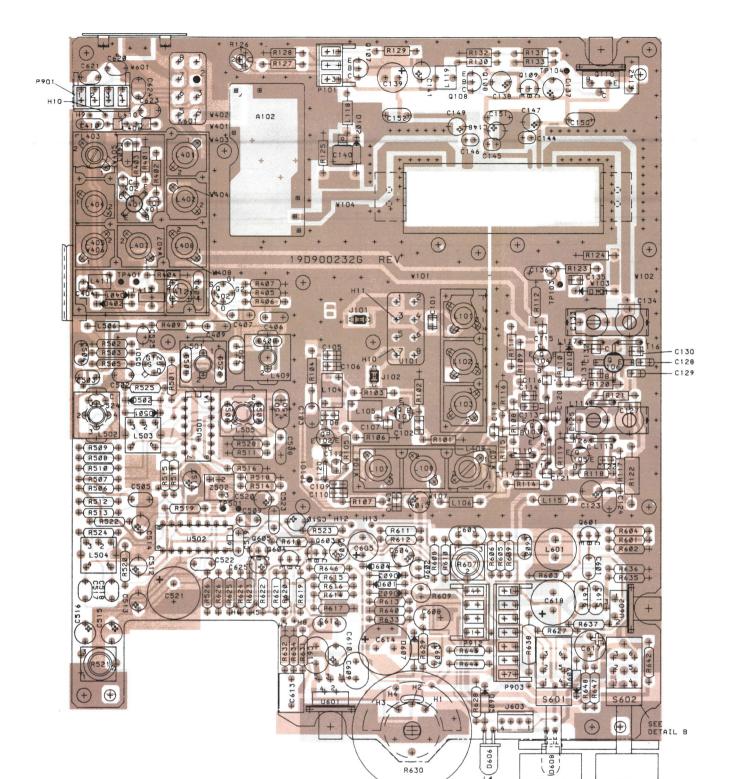




OUTLINE DIAGRAM

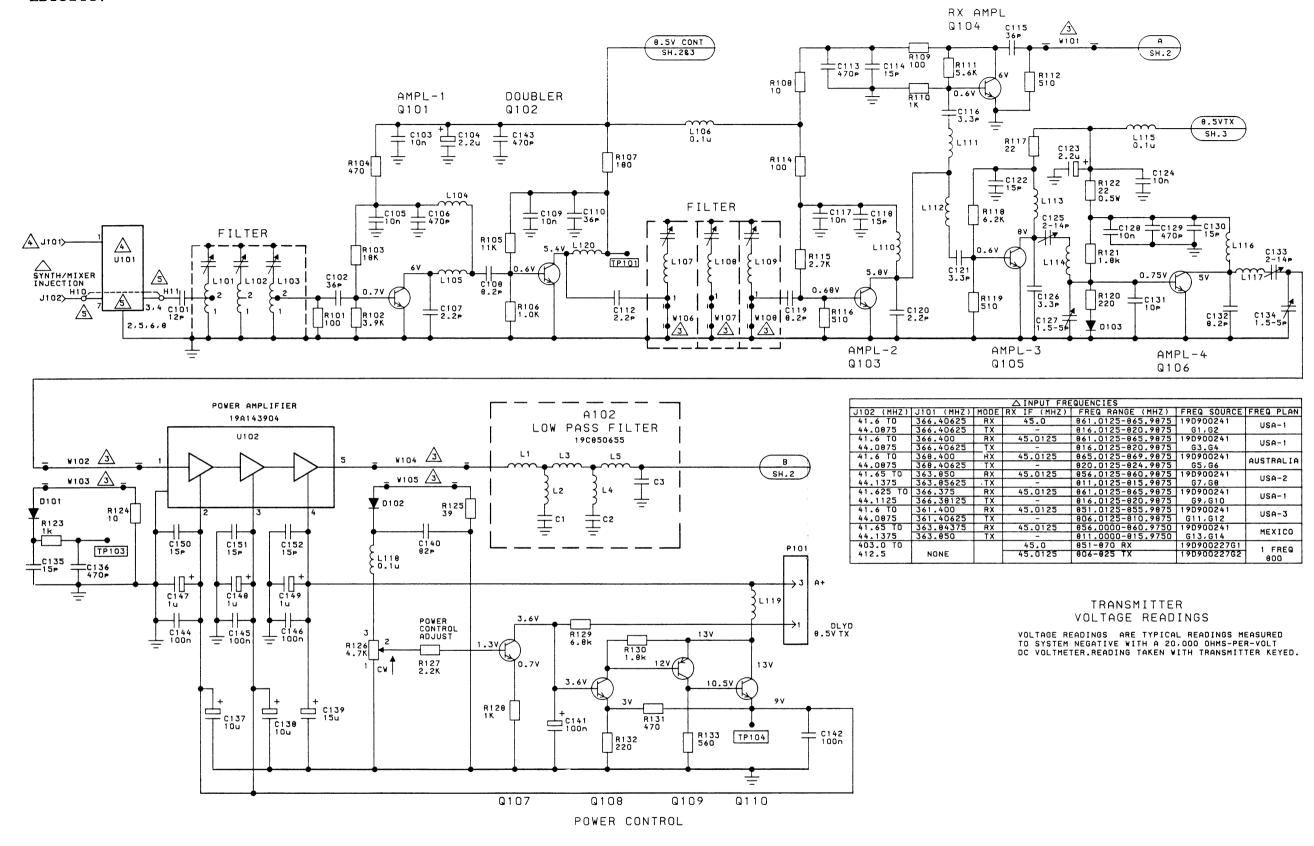
TRANSMITTER/RECEIVER BOARD (15 Watt Simplex)

Issue 1





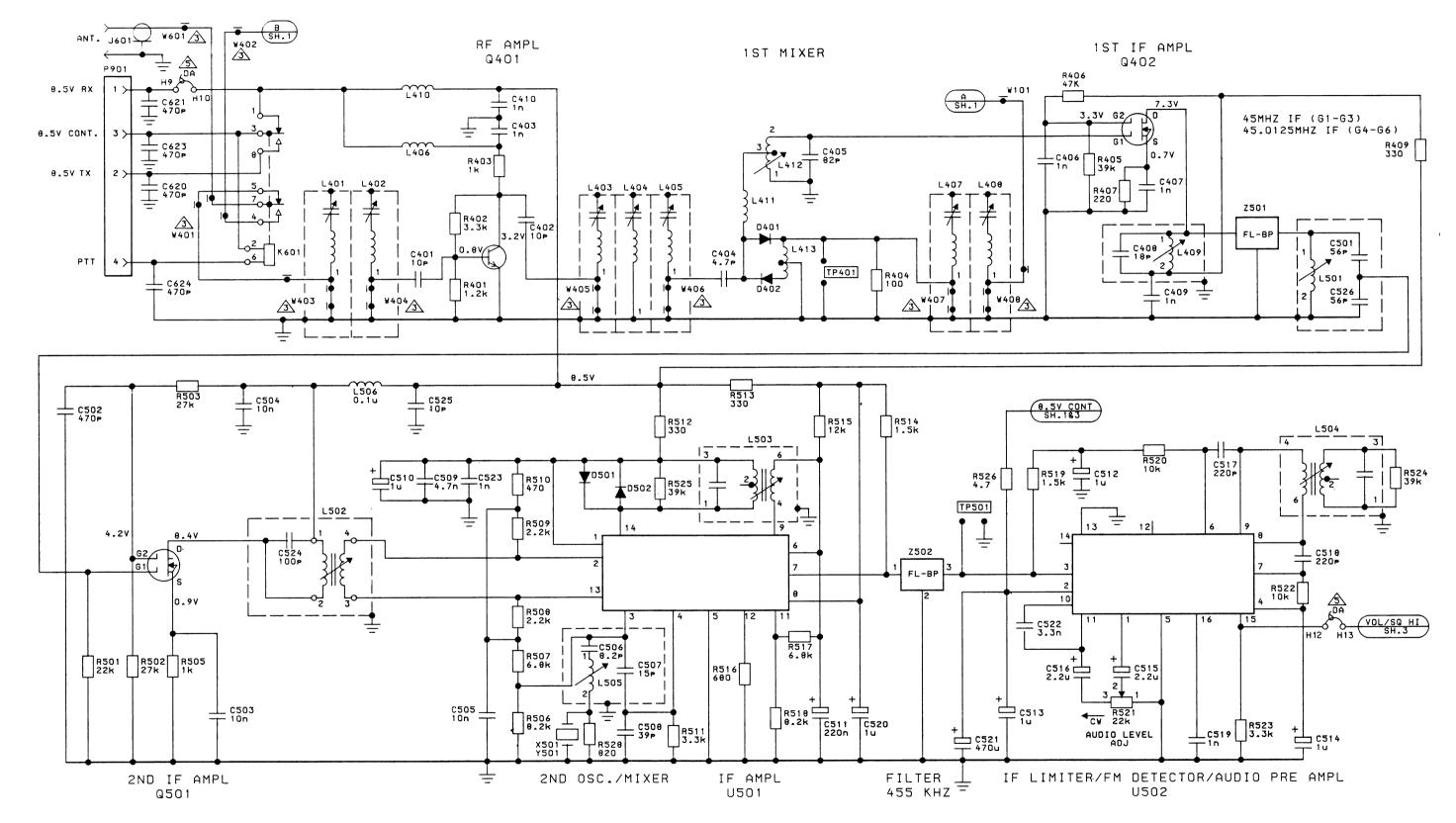
(19D900233, Rev. 16) (19A701520, Sh. 1, Rev. 6) (19A701520, Sh. 2, Rev. 6)



SCHEMATIC DIAGRAM

TRANSMITTER/RECEIVER BOARD (15 Watt Simplex)

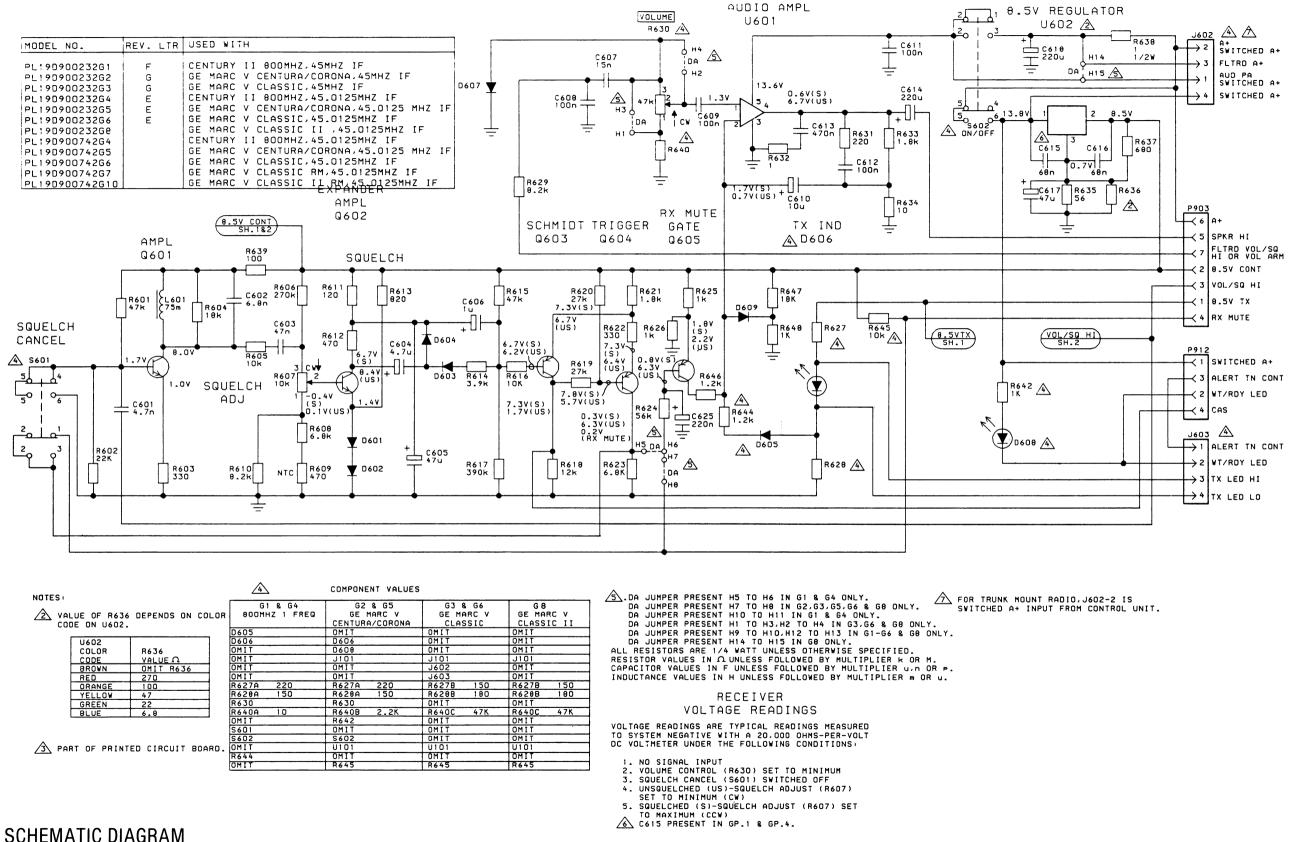
(19D900348, Sh. 1, Rev. 11)



(19D900348, Sh. 2, Rev. 4)

SCHEMATIC DIAGRAM

TRANSMITTER/RECEIVER BOARD (15 Watt Simplex)



TRANSMITTER/RECEIVER BOARD (15 Watt Simplex)

(19D900348, Sh. 3, Rev. 16)

		PARTS LIST	
800	MHz	TRANSMIT/RECEIVE ASSEMBLY, 15 WATT SIMPLEX 19D900742G10 ISSUE 1	

YMBOL	GE PART NO.	DESCRIPTION
A2		TRANSMIT/RECEIVE BOARD 19D900232G8
A102		LOW PASS FILTER BOARD 19C850655G2
L3	19A701782P1	Coil.
L5	19A701782P1	Coil.
C101	194700219930	Ceramic: 12 pF ±5%, 100 VDCW, temp coef 0 PPM.
C102	19A700219P48	Ceramic: 36 pF ±5%, 100 VDCW, temp coef 0 PPM.
C103	19A700234P7	Polyester: 0.01 uF ±10%, 50 VDCW.
C104	19A701534P5	Tantalum: 2.2 uF, ±20%, 35 VDCW.
C105	19A116192P1	Ceramic: 0.01 uF ±20%, 50 VDCW; sim to Erie 8121 SPECIAL.
C106	19A116192P2	Ceramic: 470 pF ±20%, 50 VDCW; sim to Erie 811-A050-W5R-471M.
C107	19A700219P10	Ceramic: 2.2 pF ±5%, 100 VDCW, temp coef 0 PPM.
C108	19A700219P24	Ceramic: 8.2 pF ±5%, 100 VDCW, temp coef 0 PPM.
C109	19A116192P1	Ceramic: 0.01 uF ±20%, 50 VDCW; sim to Erie 8121 SPECIAL.
C110	19A700219P48	Ceramic: 36 pF ±5%, 100 VDCW, temp coef 0 PPM.
C112	19A700219P10	Ceramic: 2.2 pF ±5%, 100 VDCW, temp coef 0 PPM.
C113	19A116192P2	Ceramic: 470 pF ±20%, 50 VDCW; sim to Erie 811-A050-W5R-471M.
C114	19A700219P33	Ceramic: 15 pF ±5%, 100 VDCW, temp coef 0 PPM.
C115	19A700219P48	Ceramic: 36 pF ±5%, 100 VDCW, temp coef 0 PPM.
C116	19A700219P14	Ceramic: 3.3 pF ±5%, 100 VDCW, temp coef 0 PPM.
C117	19A116192P1	Ceramic: 0.01 uF ±20%, 50 VDCW; sim to Erie 8121 SPECIAL.
C118	19A700219P33	Ceramic: 15 pF ±5%, 100 VDCW, temp coef 0 PPM.
C119	19A700219P24	Ceramic: 8.2 pF ±5%, 100 VDCW, temp coef 0 PPM.
C120	19A700219P10	Ceramic: 2.2 pF ±5%, 100 VDCW, temp coef 0 PPM.
C121	19A700219P14	Ceramic: 3.3 pF ±5%, 100 VDCW, temp coef 0 PPM.
C122	19A700219P33	Ceramic: 15 pF ±5%, 100 VDCW, temp coef 0 PPM.
C123	19A701534P5	Tantalum: 2.2 uF, ±20%, 35 VDCW.
C124 C125	19A700234P7 19A700008P2	Polyester: 0.01 uF ±10%, 50 VDCW. Variable: 2.28 to 14.13 pF; sim to EF Johnson
		187-0109-005.
C126	19A700219P14	Ceramic: 3.3 pF ±5%, 100 VDCW, temp coef 0 PPM.
C127	19A700008P3	Variable, air: 1.56 to 4.86 pF; sim to EF Johnson 187-0103-005.
C128	19A116192P1	Ceramic: 0.01 uF ±20%, 50 VDCW; sim to Erie 8121 SPECIAL.
C129	19A116192P2	Ceramic: 470 pF +20%, 50 VDCW; sim to Erie 811-A050-W5R-471M.
C130	19A700219P33	Ceramic: 15 pF +5%, 100 VDCW, temp coef 0 PPM.
C131	19A700219P26	Ceramic: 10 pF ±5%, 100 VDCW, temp coef 0 PPM.
C132	19A700219P24	Ceramic: 8.2 pF ±5%, 100 VDCW, temp coef 0 PPM.
C133	19A700008P2	Variable: 2.28 to 14.13 pF; sim to EF Johnson 187-0109-005.

SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DES
C134	19A700008P3	Variable, air: 1.56 to 4.86 pF; sim to EF	C601	19A700234P5	Polyester: 4700 pF <u>+</u> 10%, 50 VDCW.	L106	19B209420P101	Coil, RF: .10 uH + to Jeffers 4416-1K.
C135	194700219933	Johnson 187-0103-005. Ceramic: 15 pF +5%, 100 VDCW, temp coef 0 PPM.	C602	19A700234P6	Polyester: 6800 pF ±10%, 50 VDCW.	L107	19B233593P4	Coil, RF: sim to Pa
C135	194700219133	Ceramic disc: $470 \text{ pF} \pm 10\%$, 1000 VDCW ; sim to RMC	C603	19A700234P11	Polyester: 0.047 uF ±10%, 50 VDCW.	thru L109		
C136	194116655714	Type JF Discap.	C604	19A701534P6	Tantalum: 4.7 uF ±20%, 35 VDCW.	L110	19A701524P1	Coil.
C137 and	19A701534P7	Tantalum: 10 uF <u>+</u> 20%, 16 VDCW.	C605	19A134730P1	Electrolytic: 47 uF +100 -10%, 16 VDCW.	L111	19A701524P5	Coil.
C138			C606	19A701534P4	Tantalum: 1 uF ±20%, 35 VDCW.	L112	19A701524P2	Coil.
C139	19A701225P1	Electrolytic: 15 uF -10 +75%, 25 VDCW; sim to Sprague 501D156-G025BB1C.	C607	19A700234P8	Polyester: .015 uF ±10%, 50 VDCW; sim to NISSEI AMXV or AMZV.	L113	19A701524P3	Coil.
C140	19A700006P32	Mica: 82 pF +5%, 100 VDCW; sim to Underwood	C608	19A700234P13	Polyester: 0.1 uF +10%, 50 VDCW.	L114	19A701524P1	Coil.
		3HS0020.	and C607			L115	19B209420P101	Coil, RF: .10 uH +:
C141	19A701534P1	Tantalum: 0.1 uF <u>+</u> 20%, 35 VDCW.	C610	19A701534P7	Tantalum: 10 uF <u>+</u> 20%, 16 VDCW.	L116	19A701524P4	Coil.
C142	19A700004P2	Metallized polyester: 0.1 uF ±10%, 63 VDCW.	C611	19A700234P13	Polyester: 0.1 uF +10%, 50 VDCW.	L117	19A701524P4 19A701524P1	Coil.
C143	19A116192P2	Ceramic: 470 pF +20%, 50 VDCW; sim to Erie 811-A050-W5R-471M.	C612	19A702250P113	Polyester: 0.1 uF ±10%, 50 VDCW.	L118	19B209420P101	Coil, RF: .10 uH ±
C144	19A143565P8	Ceramic: 0.1 uF <u>+</u> 10%, 50 VDCW.	C613	19A700004P6	Metallized Polyester: 0.47 <u>+</u> 10%, 63 VDCW.	1 110	1302034207101	to Jeffers 4416-1K.
thru C146			C614	19A134730P2	Electrolytic: 220 uF +100 -10%, 25 VDCW.	L119	19A138298P1	Coil.
C147	19A701534P4	Tantalum: 1 uF <u>+</u> 20%, 35 VDCW.	C615	19A700234P12	Polyester: 0.068 uF <u>+</u> 10%, 50 VDCW.	L120	19A702028P2	Coil.
thru C149			and C616			L401 and	19B233593P2	Coil, RF: sim to P
C150	19A116656P15J0	Ceramic disc: 15 pF ±5%, 500 VDCW, temp coef	C617	19A134730P1	Electrolytic: 47 uF +100 -10%, 16 VDCW.	L402		
thru C152		О РРМ.	C618	19A134730P2	Electrolytic: 220 uF +100 -10%, 25 VDCW.	L403	19B233593P1	Coil, RF: sim to Pa
C401	19A700219P26	Ceramic: 10 pF ±5%, 100 VDCW, temp coef 0 PPM.	C620	19A700233P5	Ceramic: 470 pF <u>+</u> 20%, 50 VDCW.	L404	19B233593P2	Coil, RF: sim to Pa
and C402		-	and C621			L405	19B233593P1	Coil, RF: sim to Pa
C403	19A700233P7	Ceramic: 1000 pF <u>+</u> 20%, 50 VDCW.	C623	19A700233P5	Ceramic: 470 pF ±20%, 50 VDCW.	L406	19A138400G1	Coil.
C404	19A700219P18	Ceramic: 4.7 pF ±5%, 100 VDCW, temp coef 0 PPM.	and C624			L407	19B233593P3	Coil, RF: sim to Pa
C405	19A700235P24	- Ceramic: 82 pF ±5%, 50 VDCW.	C625	19A701534P2	Tantalum: 0.22 uF <u>+</u> 20%, 35 VDCW.	and L408		
C406	19A700233P7	Ceramic: 1000 pF ±20%, 50 VDCW.			210070	L409	19A134729P4	Coil, RF: sim to Pa
and C407		_				L410	19A138400G1	Coil.
C408	19A700235P16	Ceramic: 18 pF <u>+</u> 5%, 50 VDCW.	D101	19A116052P1	Silicon, hot carrier: Fwd drop .350 volts max.	L411	19A136535P1	Coil.
C409	19A700233P7	Ceramic: 1000 pF ±20%, 50 VDCW.	D102	19A116052P2	Silicon, hot carrier: Fwd. drop .410 volts max.	L412	19J706083P23	Coil, RF: variable.
and C410		_	D103	19A115100P2	Silicon; sim to Type 1N459A.	L413	19A701768G1	Coil.
C501	19A700235P22	Ceramic: 56 pF <u>+</u> 5%, 50 VDCW.	D401	19A116052P4	Silicon, hot carrier: Fwd. drop .350 volts max. (Includes D402).	L501	19A134729P4	Coil, RF: sim to Pa
C502	19A700233P5	Ceramic: 470 pF <u>+</u> 20%, 50 VDCW.	D402		(Part of D401).	L502	19B800691P1	Coil, RF: single po
C503	19A700234P7	Polyester: 0.01 uF <u>+</u> 10%, 50 VDCW.	D501	19A700028P1	Silicon, fast recovery: fwd current 75 mA,	L503	19A134747P1	Transformer, IF: 4
thru C505			and D502		75 PIV; sim to Type 1N4148.	and L504		
C506	19A700235P12	Ceramic: 8.2 pF ±0.25 pF, 50 VDCW.	D601	19A700028P1	Silicon, fast recovery: fwd current 75 mA,	L505	19J706029P4	Coil, RF: variable
C507	19A700235P15	Ceramic: 15 pF ±5%, 50 VDCW.	thru D604		75 PIV; sim to Type 1N4148.	L506	19A700024P1	Coil, RF: 100 nH ±
C508	19A700235P20	Ceramic: 39 pF ±5%, 50 VDCW.	D607	19A700028P1	Silicon, fast recovery: fwd current 75 mA,	L601	19A134741P1	Reactor, (Audio Fre
C509	19A700234P5	Polyester: 4700 pF <u>+</u> 10%, 50 VDCW.			75 PIV; sim to Type 1N4148.	1601	19813474171	Reactor, (Audio Free
C510	19A701534P4	Tantalum: 1 uF <u>+</u> 20%, 35 VDCW.	D609	19A700028P1	Silicon, fast recovery: fwd current 75 mA, 75 PIV; sim to Type 1N4148.			
C511	19A701534P2	Tantalum: 0.22 uF <u>+</u> 20%, 35 VDCW.				P101	19A116659P1	Connector, printed 5 amps; sim to Mole:
C512	19A701534P4	Tantalum: 1 uF <u>+</u> 20%, 35 VDCW.			Contact, electrical; sim to AMP 86444-1. (Strip	P901	19A116659P15	Connector, printed
thru C514			J101 and	19A701883P4	Form).	7501	134110033713	5 amps; sim to Mole
C515	19A701534P5	Tantalum: 2.2 uF, <u>+</u> 20%, 35 VDCW.	J102	1041100500102	Connector, printed wiring: 4 contacts rated at	P903	19A116659P83	Connector, printed 5 amps; sim to Mole:
and C516			J602	19A116659P103	5 amps; sim to Molex 09-60-1041.	P912	19A116659P15	Connector, printed
C517	19A700233P3	Ceramic: 220 pF ±10%, 50 VDCW.	J603	19A700072P30	Connector, printed wiring: 4 contacts rated at 2.5 amps; sim to Molex 22-27-2041.	7512	134110003110	5 amps; sim to Mole:
and C518					2.0 amps, sim to moter 22 2. 2011.			
C519	19A700233P7	Ceramic: 1000 pF <u>+</u> 20%, 50 VDCW.		i	RELAYS	Q101	19A134336P1	Silicon, NPN.
C520	19A701534P4	Tantalum: 1 uF ±20%, 35 VDCW.	к601	19A700061P1	Hermetic sealed: 180 to 341 ohms coil res, 8-16.3 VDC: sim to GE 3SAV1760A2, CP Clare	thru Q105	10.10.0001	
C521	19A134730P3	Electrolytic: 470 uF +100 -10%, 16 VDCW.		1	HFW-1201558, or Potter-Brumfiled HCM6160.	Q106	19A134697P1	Silicon, NPN.
C522	19A700234P4	Polyester: 3300 pF <u>+</u> 10%, 50 VDCW.			INDUCTORS	Q107	19A700023P2	Silicon, NPN; sim
C523	19A700233P7	Ceramic: 1000 pF <u>+</u> 20%, 50 VDCW.	L101	19J706154P10	RF Coil: sim to Paul Smith SK802-1.	and Q108		1
C524	19A700002P25	Ceramic disc: 100 pF <u>+</u> 5%, 50 VDCW; temp coef -150 +60 PPM.	thru L103	100,00101110		Q109	19A700022P1	Silicon, PNP; sim to
C525	19A700235P13	-150 +60 PPm. Ceramic: 10 pF ±5%, 50 VDCW.	L103	19J706085P4	Coil, RF: 0.065 uH ind., ±5%; sim to Paul Smith	Q110	19A116742P1	Silicon, NPN.
C525 C526	19A700235P13	Ceramic: 10 pr ±5%, 50 vDCw. Ceramic: 56 pF ±5%, 50 VDCW.	1104	100.000014	LM-2.	Q401	19A134336P1	Silicon, NPN.
Caze	194/00235422	Seramic. So pr 13,6, 30 vice.	L105	19J706085P8	Coil, RF: 0.110 uH ind., ±5%; sim to Paul Smith LM-2.	Q402	19A116818P1	N Channel, field ef
						Q501	19A116818P1	N Channel, field ef
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SYMBOL	GE PART NO.	DESCRIPTION
L106	19B209420P101	Coil, RF: .10 uH ±10%, 0.8 ohms DC res max; sim to Jeffers 4416-1K.
L107 thru L109	19B233593P4	Coil, RF: sim to Paul Smith SK-832-1.
L110	19A701524P1	Coil.
L111	19A701524P5	Coil.
L112	19A701524P2	Coil.
L113	19A701524P3	Coil.
L114	19A701524P1	Coil.
L115	19B209420P101	Coil, RF: .10 uH \pm 10%, 0.8 ohms DC res max; sim to Jeffers $4416-1\mathrm{K}^-$
L116	19A701524P4	Coil.
L117	19A701524P1	Coil.
L118	19B209420P101	Coil, RF: .10 uH ±10%, 0.8 ohms DC res max; sim to Jeffers 4416-1K.
L119	19A138298P1	Coil.
L120	19A702028P2	Coil.
L401 and L402	19B233593P2	Coil, RF: sim to Paul Smith SK-832-1.
L403	19B233593P1	Coil, RF: sim to Paul Smith SK-832-1.
L404	19B233593P2	Coil, RF: sim to Paul Smith SK-832-1.
L405	19B233593P1	Coil, RF: sim to Paul Smith SK-832-1.
L406	19A138400G1	Coil.
L407 and	19B233593P3	Coil, RF: sim to Paul Smith SK-832-1.
	10413479004	Coil DE, oim to Doul Cmith CV 939 1
		Coil, RF: sim to Paul Smith SK-832-1.
		Coil.
		Coil.
L412	19J706083P23	Coil, RF: variable.
L413	19A701768G1	Coil.
L501	19A134729P4	Coil, RF: sim to Paul Smith SK-832-1.
L502	19B800691P1	Coil, RF: single pole, wire size No. 24 AWG.
L503 and L504	19A134747P1	Transformer, IF: 455 KHz.
L505	19J706029P4	Coil, RF: variable; sim to Paul Smith EF223.
L506	19A700024P1	Coil, RF: 100 nH ±10%, 0.08 ohms DC res max, 100 v.
L601	19A134741P1	Reactor, (Audio Freq): 75 nH ±10%.
P101	19A116659P1	Connector, printed wiring: 3 contacts rated at 5 amps; sim to Molex 09-52-3032.
P901	19A116659P15	Connector, printed wiring: 4 contacts rated at 5 amps; sim to Molex 09-52-3042.
P903	19A116659P83	Connector, printed wiring: 7 contacts rated at 5 amps; sim to Molex 09-52-3072 SPECIAL.
P912	19A116659P15	Connector, printed wiring: 4 contacts rated at 5 amps; sim to Molex 09-52-3042.
Q101	19A134336P1	
Q105		
Q106	19 A 134697P1	Silicon, NPN.
Q107 and Q108	19A700023P2	Silicon, NPN; sim to Type 2N3904.
Q109	19A700022P1	Silicon, PNP; sim to Type 2N3906.
Q110	19A116742P1	Silicon, NPN.
Q401	19A134336P1	Silicon, NPN.
Q402	19A116818P1	N Channel, field effect.
	L107 thru L109 L110 L111 L112 L113 L114 L115 L116 L117 L118 L119 L120 L401 and L402 L403 L404 L405 L406 L407 and L408 L409 L410 L411 L412 L413 L501 L502 L503 and L504 L505 L506 L601 P101 P901 P903 P912 Q101 thru Q105 Q106 Q107 and Q108 Q109 Q110	L107 thru L109 L110 19A701524P1 L111 19A701524P2 L111 19A701524P3 L114 19A701524P1 L115 19B209420P101 L116 19A701524P1 L117 19A701524P1 L118 19B209420P101 L119 19A138298P1 L120 19A702028P2 L401 19B233593P2 L402 L403 19B233593P2 L404 19B233593P2 L405 19B233593P1 L406 19A138400G1 L407 19B233593P1 L408 L409 19A134729P4 L410 19A138400G1 L411 19A136535P1 L412 19J706083P23 L413 19A701768G1 L501 19A13472P4 L502 19B800691P1 L503 19A13474P1 L504 L505 19J70602P4 L506 19A700024P1 L601 19A13474P1 P101 19A116659P15 P903 19A116659P15 P903 19A116659P15 P901 19A134697P1 19A13653P1 19A13474P1 P101 19A116659P15 P903 19A116659P15 P901 19A116659P15 P903 19A116659P15 P903 19A116659P15 P901 19A134697P1 19A134697P1 19A134697P1 19A700023P2 q106 19A700022P1

SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION
Q601	19A116774P3	Silicon, NPN; sim to Type 2N5210.	R510	19A700019P33	Deposited carbon: 470 ohms ±5%, 1/4 w.	R636B	19A700019P25	Deposited carbon: 100 ohms ±5%, 1/4 w.		19A701874P1	Tab. (Located under W102 & W104 solder side of
and Q602			R511	19A700019P43	Deposited carbon: 3.3K ohms ±5%, 1/4 w.	R636C	19A700019P21	Deposited carbon: 47 ohms ±5%, 1/4 w.		19A138451P1	board). Tuning slug. (Used with L101-L103 & L107-L109).
Q603 thru	19A134749P1	Silicon, PNP; sim to Type 2N5087.	R512 and	19A700019P31	Deposited carbon: 330 ohms ±5%, 1/4 w.	R636D	19A700019P17	Deposited carbon: 22 ohms ±5%, 1/4 w.		19A701886P1	Spring. (Used with L107-L109, L401-L407, L409,
Q605			R513			R636E	19A700019P11	Deposited carbon: 6.8 ohms ±5%, 1/4 w.		150100011	L412 & L501).
			R514	19A700019P39	Deposited carbon: 1.5K ohms $\pm 5\%$, 1/4 w.	R637	19A700019P35	Deposited carbon: 680 ohms ±5%, 1/4 w.		19A701785P5	Contact, electrical. (Located at A102 - Quantity 6).
R101	19A700106P39	Composition: 100 ohms ±5%, 1/4 w.	R515	19A700019P50	Deposited carbon: 12K ohms $\pm 5\%$, 1/4 w.	R638	19A700018P1	Deposited carbon: 1 ohm ±5%, 1/3 w.		19A702364P208	Machine screw, metric: 2.545 x 10MM. (Secures
R102	19A700106P77	Composition: 3.9K ohms ±5%, 1/4 w.	R516	19A700019P35	Deposited carbon: 680 ohms ±5%, 1/4 w.	R639	19A700019P25	Deposited carbon: 100 ohms ±5%, 1/4 w.			Q110, U601 & U602).
R103	19A700106P93	Composition: 18K ohms ±5%, 1/4 w.	R517	19A700019P47	Deposited carbon: 6.8K ohms ±5%, 1/4 w.	R640	19A700019P57	Deposited carbon: 47K ohms ±5%, 1/4 w.		19A700034P3	Hex nut, metric: M2.5 x 0.45. (Secures Q110, U601 & U602).
R104	19A700106P55	Composition: 470 ohms $\pm 5\%$, $1/4$ w.	R518	19A700019P48	Deposited carbon: 8.2K ohms ±5%, 1/4 w.	R645	19A700019P49	Deposited carbon: 10K ohms ±5%, 1/4 w.		19A700032P3	Lockwasher, tooth, steel, metric: 2.5. (Secures
R105	3R152P113J	Composition: 11K ohms ±5%, 1/4 w.	R519	19A700019P39	Deposited carbon: 1.5K ohms ±5%, 1/4 w.	R646	19A700019P38	Deposited carbon: 1.2K ohms ±5%, 1/4 w.			Q110, U601 & U602).
R106	19A700106P63	Composition: 1K ohms ±5%, 1/4 w.	R520	19A700019P49	Deposited carbon: 10K ohms ±5%, 1/4 w.	R647	19A700019P52	Deposited carbon: 18K ohms ±5%, 1/4 w.		19A702381P508	Screw, thd. form: No. 3.5-0.6 x 8. (Secures printed board).
R107	19A700106P45	Composition: 180 ohms ±5%, 1/4 w.	R521	19B800784P209	Variable: 10K ohms ±20%, 1/2 w; sim to Murata Type RVG0911V328.	R648	19A700019P37	Deposited carbon: 1K ohms ±5%, 1/4 w.		19A138451P2	Spring. (Used with L401-L405, L407, & L408).
R108	19A700106P15	Composition: 10 ohms ±5%, 1/4 w.	R522	19A700019P49	Deposited carbon: 10K ohms $\pm 5\%$, 1/4 w.					19A702364P106	Machine screw: TORX®Drive, No. M2-0.4 x 6.
R109	19A700106P39	Composition: 100 ohms ±5%, 1/4 w.	R523	19A700019P43	Deposited carbon: 3.3K ohms ±5%, 1/4 w.	TP101	19A700152P1	Contact.			(Quantity 18).
R110	19A700106P63	Composition: 1K ohms ±5%, 1/4 w.	R524	19A700019P56	Deposited carbon: 39K ohms $\pm 5\%$, 1/4 w.	TP103	19A700152P1	Contact.		19C850671P1	Ground strap.
R111	19A700106P81	Composition: 5.6K ohms ±5%, 1/4 w.	and R525			TP104	19A700152P1	Contact.		19A700115P3	Insulator, plate.
R112	3R152P511J	Composition: 510 ohms ±5%, 1/4 w.	R526	19A700019P9	Deposited carbon: 4.7 ohms $\pm 5\%$, $1/4$ w.	TP401	19A700152P1	Contact. (Quantity 2).		19A700068P1	Insulator, bushing.
R114	19A700106P39	Composition: 100 ohms ±5%, 1/4 w.	R528	19A700019P36	Deposited carbon: 820 ohms $\pm 5\%$, 1/4 w.	TP501	19A700152P1	Contact. (Quantity 2).			
R115	19A700106P73	Composition: 2.7K ohms ±5%, 1/4 w.	R601	19A700019P57	Deposited carbon: 47K ohms ±5%, 1/4 w.	1		INTEGRATED CIRCUITS			l i
R116	3R152P511J	Composition: 510 ohms ±5%, 1/4 w.	R602	19A700019P53	Deposited carbon: 22K ohms $\pm 5\%$, 1/4 w.	U101	1000000000				
R117	19A700106P23	Composition: 22 ohms ±5%, 1/4 w.	R603	19A700019P31	Deposited carbon: 330 ohms ±5%, 1/4 w.	U501	19B209680P1 19A134759P1	Mixer, balanced. Linear, Dual Differential Amplifier, 14 Pin Dip.			
R118	3R152P622J	Composition: 6200 ohms ±5%, 1/4 w.	R604	19A700019P52	Deposited carbon: 18K ohms ±5%, 1/4 w.		19A134766P1	ł i			
R119	3R152P511J	Composition: 510 ohms ±5%, 1/4 w.	R605	19A700019P49	Deposited carbon: 10K ohms ±5%, 1/4 w.	U502		Linear, Outline For 16-Pin Dip case.			
R120	19A700106P47	Composition: 220 ohms ±5%, 1/4 w.	R606	19A700019P66	Deposited carbon: 0.27M ohms ±5%, 1/4 w.	U601	19A134769P2	Linear: sim to TDA 2002.		1	1
R121	19A700106P69	Composition: 1.8K ohms ±5%, 1/4 w.	R607	19B800784P208	Variable: 10K ohms +20%, 1/2 w; sim to Murata	U602	19A138414G1	Regulator: 8.5 V.			
R122	19A700113P23	Composition: 22 ohms ±5%, 1/2 w.	P.CO.S	104700010047	Type RVG0911V328.						
R123	19A700106P63	Composition: 1K ohms ±5%, 1/4 w.	R608	19A700019P47	Deposited carbon: 6.8K ohms +5%, 1/4 w.	W 101		Microstrip inductor. (Part of printed board			
R124	19A700106P15	Composition: 10 ohms ±5%, 1/4 w.	R609	19A701828P2	Thermistor: 470 ohms $\pm 20\%$; sim to Phillips 2322-642-61471.	thru W 108		19D901259P1).		i	1
R125	19A700106P29	Composition: 39 ohms ±5%, 1/4 w.	R610	19A700019P48	Deposited carbon: 8.2K ohms ±5%, 1/4 w.	W401 thru		Microstrip inductor. (Part of printed board 19D901259P1).			
R126	19A700016P3	Variable, cermet: 4.7K ohms $\pm 10\%$, 1/2 w.	R611	19A700019P26	Deposited carbon: 120 ohms ±5%, 1/4 w.	W 408		19090123971).			
R127	19A700106P71	Composition: 2.2K ohms ±5%, 1/4 w.	R612	19A700019P33	Deposited carbon: 470 ohms $\pm 5\%$, 1/4 w.	W 601		(Part of printed board 19D901259P1).		ł	
R128	19A700106P63	Composition: 1K ohms ±5%, 1/4 w.	R613	19A700019P36	Deposited carbon: 820 ohms $\pm 5\%$, 1/4 w.						1
R129	19A700106P83	Composition: 6.8K ohms ±5%, 1/4 w.	R614	19A700019P44	Deposited carbon: 3.9K ohms ±5%, 1/4 w.	X501	19A702742P1	Crystal socket. (Quantity 2).			[
R130	19A700106P69	Composition: 1.8K ohms ±5%, 1/4 w.	R615	19A700019P57	Deposited carbon: 47K ohms $\pm 5\%$, 1/4 w.		100211211	(44411210, 2)			1
R131	19A700106P55	Composition: 470 ohms $\pm 5\%$, 1/4 w.	R616	19A700019P49	Deposited carbon: 10K ohms ±5%, 1/4 w.			CRYSTALS		ł	
R132	19A700106P47	Composition: 220 ohms $\pm 5\%$, 1/4 w.	R617	19A700019P68	Deposited carbon: 0.39M ohms $\pm 5\%$, 1/4 w.			NOTE: When reordering give GE Part Number and specify exact frequency needed.	1		
R133	19A700106P57	Composition: 560 ohms ±5%, 1/4 w.	R618	19A700019P50	Deposited carbon: 12K ohms $\pm 5\%$, 1/4 w.	Y501	19B233066G9	Crystal: freq range 45.4675 MHz.			
R401	19A700106P65	Composition: 1.2K ohms ±5%, 1/4 w.	R619 and	19A700019P54	Deposited carbon: 27K ohms $\pm 5\%$, 1/4 w.			1			
R402	19A700106P75	Composition: 3.3K ohms ±5%, 1/4 w.	R620					NETW OR KS			
R403	19A700106P63	Composition: 1K ohms ±5%, 1/4 w.	R621	19A700019P40	Deposited carbon: 1.8K ohms ±5%, 1/4 w.	Z501	19B209613P3	Filter, bandpass: 45.0.125 ref freq, 13 KHz bandwidth.			
R404	19A700106P39	Composition: 100 ohms ±5%, 1/4 w.	R622	19A700019P31	Deposited carbon: 330 ohms ±5%, 1/4 w.	Z502	19A702171P1	Filter, bandpass: 455 ±1.5 kHz; sim to Murata			
R405	19A700019P56	Deposited carbon: 39K ohms ±5%, 1/4 w.	R623	19A700019P47	Deposited carbon: 6.8K ohms ±5%, 1/4 w.			CFU455D2.			1
R406	19A700019P57	Deposited carbon: 47K ohms ±5%, 1/4 w.	R624	19A700019P58	Deposited carbon: 56K ohms $\pm 5\%$, 1/4 w.			INTEGRATED CIRCUITS			
R407	19A700019P29	Deposited carbon: 220 ohms ±5%, 1/4 w.	R625 and	19A700019P37	Deposited carbon: 1K ohms <u>+</u> 5%, 1/4 w.	U101	19A143904P2	RF Amplifier.	1		
R409	19A700019P31	Deposited carbon: 330 ohms ±5%, 1/4 w.	R626								
R501	19A700019P53	Deposited carbon: 22K ohms ±5%, 1/4 w.	R627	19A700019P27	Deposited carbon: 150 ohms ±5%, 1/4 w.			MISCELLANEOUS			
R502 and	19A700019P54	Deposited carbon: 27K ohms ±5%, 1/4 w.	R628	19A700019P28	Deposited carbon: 180 ohms ±5%, 1/4 w.		19B800576P1	Shield. (Used with Q106).		ĺ	
R503			R629	19A700019P48	Deposited carbon: 8.2K ohms ±5%, 1/4 w.		19B232901P1	Support. (Secures printed board - Quantity 3).			
R505	19A700019P37	Deposited carbon: 1K ohms ±5%, 1/4 w.	R631	19A700019P29	Deposited carbon: 220 ohms ±5%, 1/4 w.		19A700069P1	Can. (Used with L409 & L501).			
R506	19A700019P48	Deposited carbon: 8.2K ohms ±5%, 1/4 w.	R632	19A700019P1	Deposited carbon: 1 ohms ±5%, 1/4 w.		19A701544P1	Can. (Used with L502 & L505).			1
R507	19A700019P47	Deposited carbon: 6.8K ohms $\pm 5\%$, $1/4 \text{ w}$.	R633	19A700019P40	Deposited carbon: 1.8K ohms ±5%, 1/4 w.		19D429946P2	Casting. (Located at L401-L407).			
R508 and	19A700019P41	Deposited carbon: 2.2K ohms ±5%, 1/4 w.	R634	19A700019P13	Deposited carbon: 10 ohms ±5%, 1/4 w.		19B850619G1	Casting. (Located at L101-L103).			
R509			R635	19A700019P22	Deposited carbon: 56 ohms ±5%, 1/4 w.		19B233285P1	Ground spring. (Located at C404).			1
	ļ		R636A	19A700019P30	Deposited carbon: 270 ohms ±5%, 1/4 w.						
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	1								1		
									1		
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